



Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-20. (Canceled)

21. (Currently Amended) An apparatus comprising:

a mounting board, on which an insulated layer is formed, a plurality of conductive patterns ~~[[are]]~~ being formed via an insulating on the insulated layer;

a hybrid integrated circuit, disposed on the mounting board, and incorporating at least one conductive path, an active element and a passive element electrically connected to the conductive path, wherein the conductive path, the active element, and the passive element are sealed by an insulating resin;

wherein a rear surface of said at least one conductive path is exposed at a surface of the insulating resin; and

an insulating film selectively formed on the rear surface of the at least one conductive path such that at least one of the conductive patterns located at a top part of the mounting board is insulated from the at least one conductive path.

22. (Previously Presented) The apparatus according to claim 21, wherein the at least one conductive path sealed by the insulating film intersects with the conductive pattern which is located at the top part of the mounting board.

23. (Previously Presented) The apparatus according to claim 21, wherein said at least one active element is connected to the conductive path by a metal wiring.

24. (Previously Presented) The apparatus according to claim 21 wherein the hybrid integrated circuit is mounted on the mounting board such that said at least one of the conductive patterns is connected to at least one of the conductive paths.

25. (Currently Amended) The apparatus according to claim 21, wherein the ~~insulating~~ insulated layer comprises a solder resist.

26. (Previously Presented) The apparatus according to claim 21, wherein the mounting board is one of a printed circuit board, a ceramic board, a flexible sheet substrate or a metal board.

27. (Currently Amended) An apparatus comprising:

a mounting board, on which an insulated layer is formed;

a plurality of conductive patterns ~~are formed via an~~ on the insulated layer and exposed at an upper surface of the mounting board;

one or more semiconductor devices disposed on the mounting board, ~~each~~ at least one of the semiconductor devices ~~device~~ comprising:

at least one conductive path; ~~[[and]]~~

a semiconductor element electrically connected to the conductive path,  
wherein the at least one conductive path and the semiconductor element are sealed by an insulating resin in such a manner that a surface of at least one of the conductive paths is exposed through the insulating resin at a rear surface of the semiconductor device; and

an insulating film selectively formed on a rear surface of the semiconductor device to insulate at least one of the exposed the conductive path surfaces from such that at least one of the conductive patterns exposed at the upper surface of ~~located at a top part of the mounting board is insulated from the conductive path.~~

28. (Currently Amended) The apparatus according to claim 27, wherein the at least one conductive path ~~sealed~~ that is insulated by the insulating film intersects with the conductive pattern which is ~~located at the top part~~ exposed at an upper surface of the mounting board.

29. (Currently Amended) The apparatus according to claim 27, wherein said one or more semiconductor devices comprises at least one active element ~~[[is]]~~ connected to at least one of the conductive ~~path~~ paths by a metal wiring.

30. (Currently Amended) The apparatus of claim 29, wherein the semiconductor device is mounted on the mounting board such that said at least one conductive pattern is connected to ~~[[the]]~~ at least one of the conductive paths ~~path~~.

31. (Previously Presented) The apparatus according to claim 27, wherein the insulating film comprises a solder resist.

32. (Previously Presented) The apparatus according to claim 27 wherein the mounting board is one of a printed circuit board, a ceramic board, a flexible sheet substrate or a metal board.

33. (Currently Amended) A method comprising:

forming a plurality of conductive patterns ~~on~~ exposed at an upper surface of a mounting board via an insulated layer;

providing a semiconductor device comprising insulating resin and at least one conductive path exposed through the insulating resin at a rear surface of the insulating resin;

forming an insulating film on ~~[[a]]~~ the rear surface of ~~[[a]]~~ the semiconductor device ~~which is sealed by an insulating resin and includes a conductive path exposed at one surface of the insulating resin,~~ so as to selectively cover at least one of the conductive ~~path~~ paths; and

mounting the semiconductor device on the mounting board such that the insulating film ~~layer~~ insulates the covered at least one conductive path from one or more ~~at least some of~~ the conductive patterns.

34. (Previously Presented) The apparatus according to claim 21, wherein the at least one conductive path includes a wiring for electrically connecting between a conductive path on

which the active element is mounted, and a conductive path on which the a passive element is mounted.

35. (Previously Presented) The apparatus according to claim 23, wherein the at least one conductive path comprises a wiring for electrically connecting between the conductive paths connected to the metal wiring.

36. (Previously Presented) The apparatus according to claim 23, wherein the at least one conductive path comprises a wiring for electrically connecting a conductive path connected to the metal wiring and a conductive path on which the active element or the passive element is mounted.